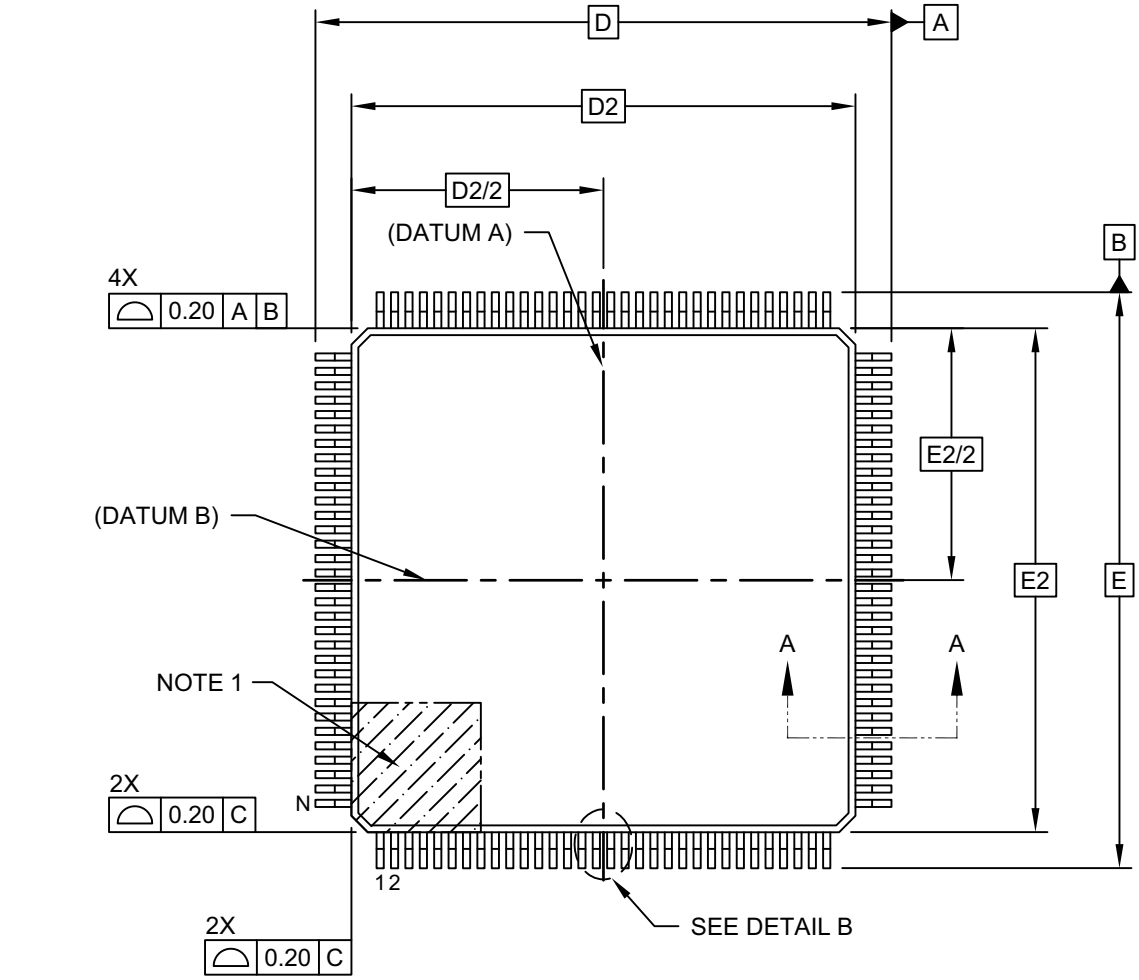
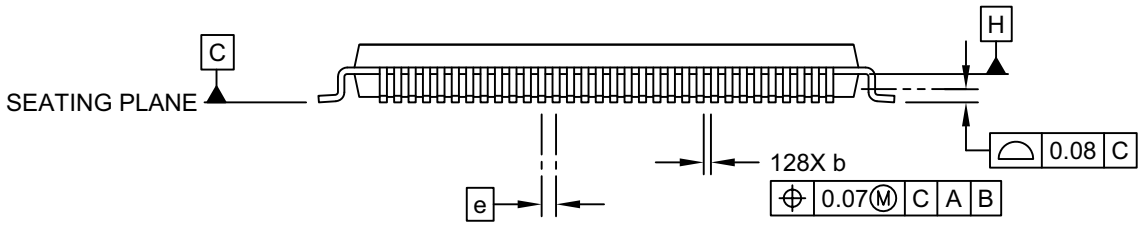
128-Lead Low Profile Plastic Quad Flat Pack (PT) – 14x14x1.4 mm Body [LQFP]

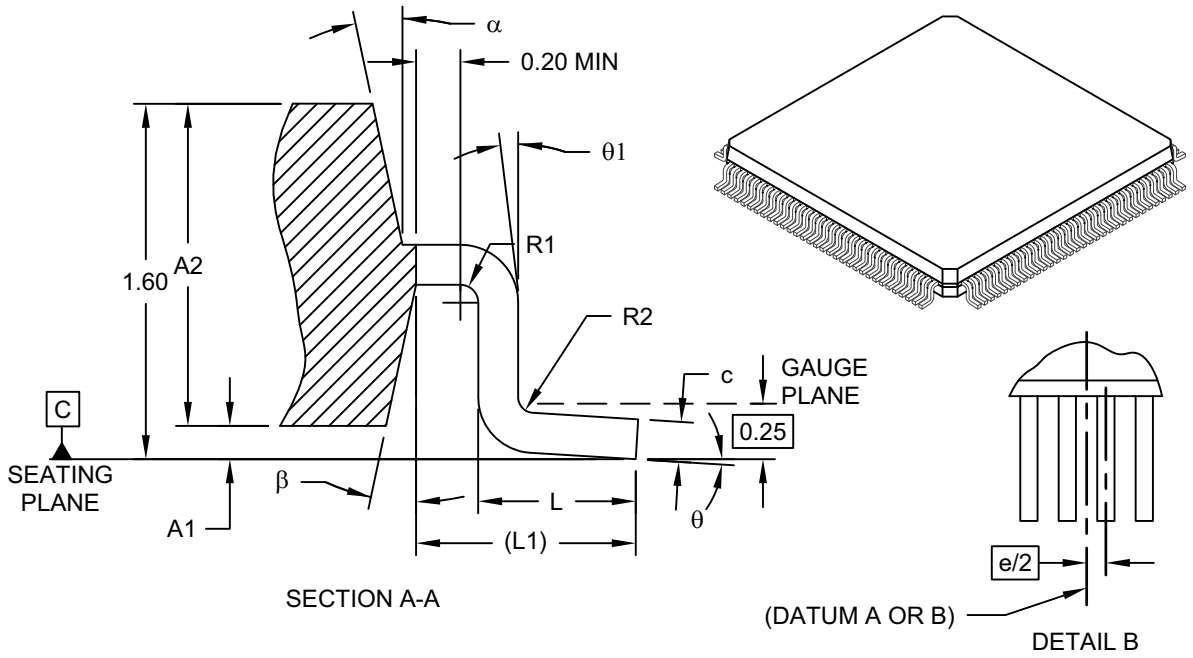
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





128-Lead Low Profile Plastic Quad Flat Pack (PT) – 14x14x1.4 mm Body [LQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX
Number of Pins	N		128	
Pitch	e		0.40 BSC	
Overall Height	A	-	-	1.60
Molded PackageThickness	A2	1.35	1.40	1.45
Standoff	A1	0.05	-	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Lead Angle	θ1	0°	3.5°	7°
Foot Angle	θ	0°	-	-
Overall Width	D		16.00 BSC	
Overall Length	E		16.00 BSC	
Molded Body Width	D1		14.00 BSC	
Molded Body Length	E1		14.00 BSC	
Lead Thickness	c	0.09	-	0.20
Lead Width	b	0.13	0.18	0.23
Bend Radius	R1	0.08	-	-
Bend Radius	R2	0.08	-	0.30
Mold Draft Angle Top	α	9°	-	11°
Mold Draft Angle Botton	β	9°	-	11°

Notes:

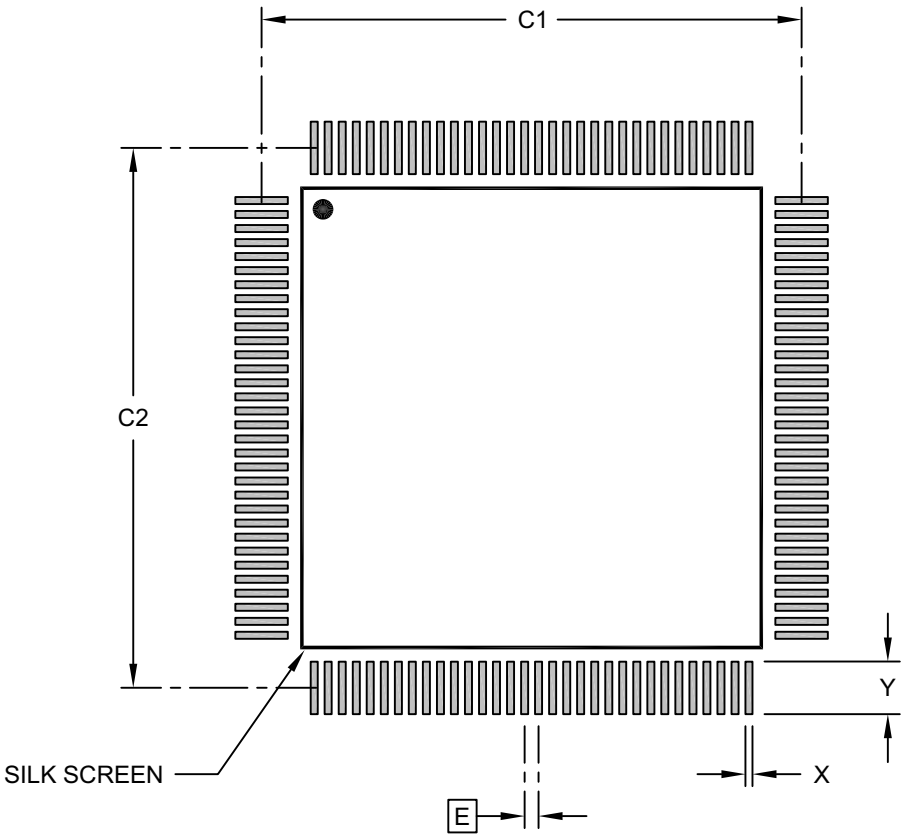
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Exact shape at each corner may vary.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

128-Lead Low Profile Plastic Quad Flat Pack (PT) – 14x14x1.4 mm Body [LQFP] 2.00 mm Footprint

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.40 BSC		
Contact Pad Spacing	C1		15.40	
Contact Pad Spacing	C2		15.40	
Contact Pad Width (X128)	X1			0.20
Contact Pad Length (X128)	Y1			1.50

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2058 Rev B